

## N-Channel Super Junction Power MOSFET IV

### General Description

The series of devices use advanced trench gate super junction technology and design to provide ultra-low  $R_{DS(ON)}$  and low gate charge and With a rapid recovery body diode. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, industrial power applications, Fast charger, new energy vehicle charging pile, on-board OBC etc.

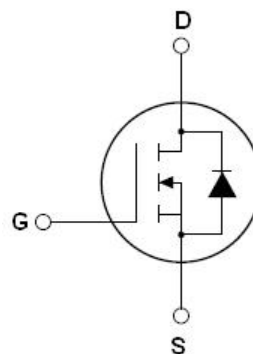
### Features

- New technology for high voltage device
- Ultra low on-resistance and ultra low conduction losses
- Ultra Low Gate Charge cause lower driving requirements
- Diode reverse recovery speed is super fast
- High reliability
- ROHS compliant

### Application

- Power factor correction (PFC)
- Switched mode power supplies (SMPS)
- Uninterruptible Power Supply (UPS)
- On-board charger (OBC)

|                        |     |    |
|------------------------|-----|----|
| $V_{DS\ min@T_{jmax}}$ | 710 | V  |
| $R_{DS(ON)TYP}$        | 85  | mΩ |
| $I_D$                  | 36  | A  |
| $Q_g$                  | 55  | nC |

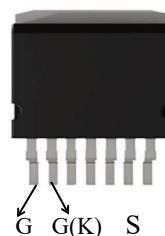


Schematic diagram

✧ Intrinsic fast-recovery body diode

### Package Marking And Ordering Information

| Device       | Device Package | Marking      |
|--------------|----------------|--------------|
| NCE65NF099D7 | TO-263-7L      | NCE65NF099D7 |



TO-263-7L

Table 1. Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ )

| Parameter  | Symbol           | Value    | Unit                |
|--|------------------|----------|---------------------|
| Drain-Source Voltage ( $V_{GS}=0V$ )                                 | $V_{DS}$         | 650      | V                   |
| Gate-Source Voltage ( $V_{DS}=0V$ ) AC ( $f>1\text{ Hz}$ )           | $V_{GS}$         | $\pm 30$ | V                   |
| Gate-Source Voltage ( $V_{DS}=0V$ ) DC                               | $V_{GS}$         | $\pm 20$ | V                   |
| Continuous Drain Current at $T_c=25^\circ\text{C}$                   | $I_D (DC)$       | 36       | A                   |
| Continuous Drain Current at $T_c=100^\circ\text{C}$                  | $I_D (DC)$       | 25.2     | A                   |
| Pulsed drain current (Note 1)  | $I_{DM (pluse)}$ | 108      | A                   |
| Maximum Power Dissipation ( $T_c=25^\circ\text{C}$ )                 | $P_D$            | 346      | W                   |
| Derate above $25^\circ\text{C}$                                      |                  | 2.30     | W/ $^\circ\text{C}$ |
| Single pulse avalanche energy (Note 2)                               | $E_{AS}$         | 484      | mJ                  |
| Avalanche current (Note 1)   | $I_{AR}$         | 11       | A                   |
| Repetitive Avalanche energy, $t_{AR}$ limited by $T_{jmax}$ (Note 1) | $E_{AR}$         | 3.9      | mJ                  |

| Parameter   | Symbol         | Value      | Unit |
|---|----------------|------------|------|
| Drain Source voltage slope, $V_{DS} \leq 480V$ ,      | dv/dt          | 50         | V/ns |
| Reverse diode dv/dt, $V_{DS} \leq 480V, I_{SD} < I_D$ | dv/dt          | 50         | V/ns |
| Operating Junction and Storage Temperature Range      | $T_J, T_{STG}$ | -55...+175 | °C   |

\* limited by maximum junction temperature

**Table 2. Thermal Characteristic**

| Parameter   | Symbol     | Value | Unit  |
|---|------------|-------|-------|
| Thermal Resistance, Junction-to-Case (Maximum)    | $R_{thJC}$ | 0.43  | °C /W |
| Thermal Resistance, Junction-to-Ambient (Maximum) | $R_{thJA}$ | 62    | °C /W |

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

| Parameter                                | Symbol              | Condition   | Min | Typ  | Max  | Unit |
|--|---------------------|---|-----|------|------|------|
| On/off states                            |                     |   |     |      |      |      |
| Drain-Source Breakdown Voltage           | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =1mA   | 650 |      |      | V    |
| Zero Gate Voltage Drain Current(Tc=25℃)  | I <sub>DSS</sub>    | V <sub>DS</sub> =650V,V <sub>GS</sub> =0V   |     |      | 10   | μA   |
| Zero Gate Voltage Drain Current(Tc=125℃) | I <sub>DSS</sub>    | V <sub>DS</sub> =650V,V <sub>GS</sub> =0V   |     |      | 400  | μA   |
| Gate-Body Leakage Current                | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V   |     |      | ±100 | nA   |
| Gate Threshold Voltage                   | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =500uA                                 | 3.5 | 4.2  | 5.0  | V    |
| Drain-Source On-State Resistance         | R <sub>Ds(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =18A   |     | 85   | 99   | mΩ   |
| Dynamic Characteristics                  |                     |   |     |      |      |      |
| Input Capacitance                        | C <sub>iss</sub>    | V <sub>DS</sub> =50V,V <sub>GS</sub> =0V,<br>F=1.0MHz                                   |     | 2800 | 3200 | pF   |
| Output Capacitance                       | C <sub>oss</sub>    |   |     | 96   |      | pF   |
| Reverse Transfer Capacitance             | C <sub>rss</sub>    |   |     | 6    |      | pF   |
| Total Gate Charge                        | Q <sub>g</sub>      | V <sub>DS</sub> =480V,I <sub>D</sub> =18A,<br>V <sub>GS</sub> =10V                      |     | 55   | 60   | nC   |
| Gate-Source Charge                       | Q <sub>gs</sub>     |   |     | 16.5 |      | nC   |
| Gate-Drain Charge                        | Q <sub>gd</sub>     |   |     | 25.5 |      | nC   |
| Gate plateau voltage                     | V <sub>gp</sub>     |   |     | 7.3  |      | V    |
| Intrinsic gate resistance                | R <sub>G</sub>      | f = 1 MHz open drain  |     | 4    |      | Ω    |
| Switching times                          |                     |   |     |      |      |      |
| Turn-on Delay Time                       | t <sub>d(on)</sub>  | V <sub>DD</sub> =380V,I <sub>D</sub> =18A,<br>R <sub>G</sub> =1.7Ω,V <sub>GS</sub> =10V |     | 15   |      | nS   |
| Turn-on Rise Time                        | t <sub>r</sub>      |   |     | 14   |      | nS   |
| Turn-Off Delay Time                      | t <sub>d(off)</sub> |   |     | 72   |      | nS   |
| Turn-Off Fall Time                       | t <sub>f</sub>      |   |     | 14   |      | nS   |
| Source- Drain Diode Characteristics      |                     |   |     |      |      |      |
| Source-drain current(Body Diode)         | I <sub>SD</sub>     | T <sub>C</sub> =25℃   |     |      | 36   | A    |
| Pulsed Source-drain current(Body Diode)  | I <sub>SDM</sub>    |   |     |      | 108  | A    |
| Forward On Voltage                       | V <sub>SD</sub>     | T <sub>J</sub> =25℃,I <sub>SD</sub> =36A,V <sub>GS</sub> =0V                            |     | 1.0  | 1.2  | V    |
| Reverse Recovery Time                    | t <sub>rr</sub>     | T <sub>J</sub> =25℃,I <sub>F</sub> =18A,di/dt=100A/μs                                   |     | 160  |      | nS   |
| Reverse Recovery Charge                  | Q <sub>rr</sub>     |   |     | 0.96 |      | uC   |
| Peak Reverse Recovery Current            | I <sub>rrm</sub>    |   |     | 12   |      | A    |

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2.  $T_J=25^\circ C, V_{DD}=50V, V_G=10V, R_G=25\Omega$

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

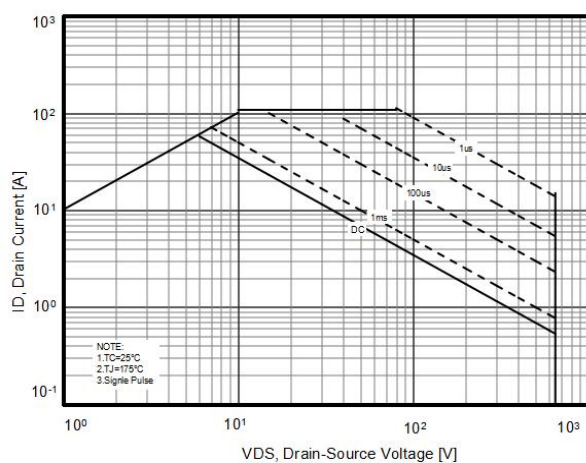


Figure2. Capacitance

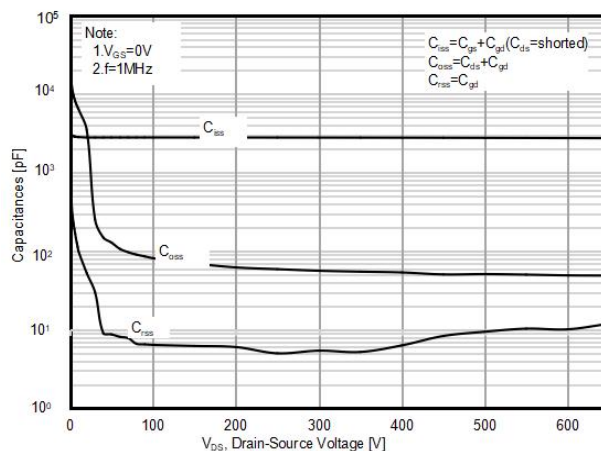


Figure3. Output characteristics

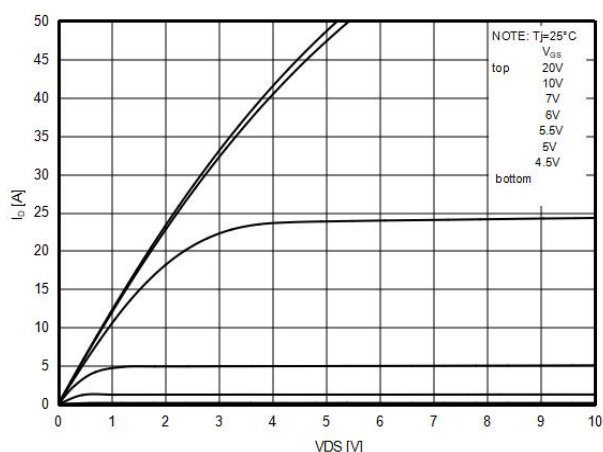


Figure4. Source-Drain Diode Forward Voltage

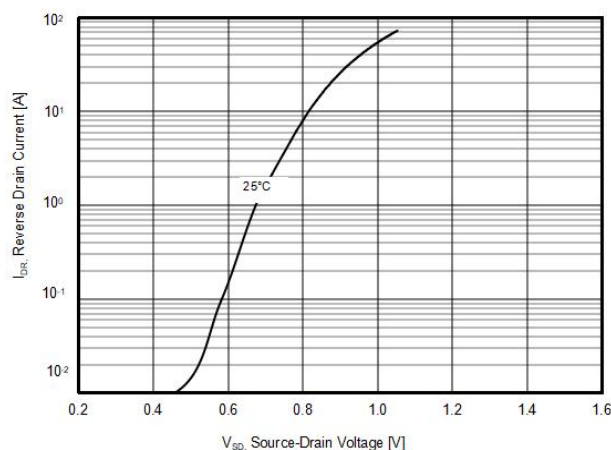


Figure5. Static drain-source on resistance

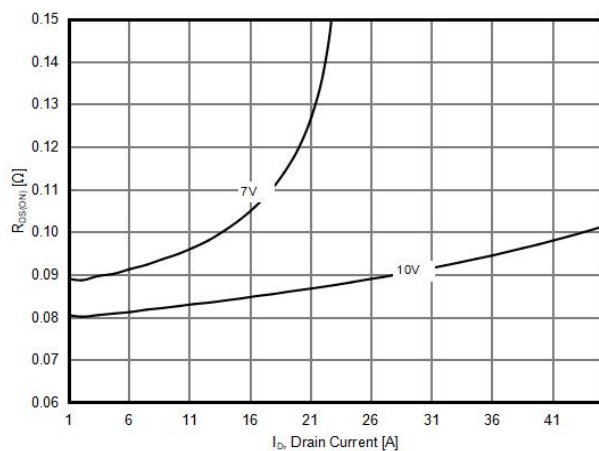
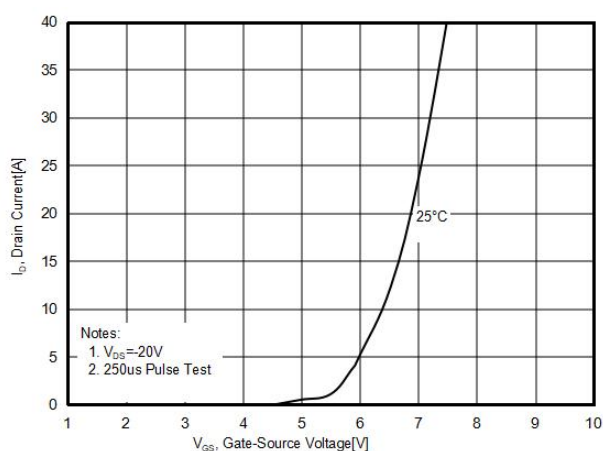
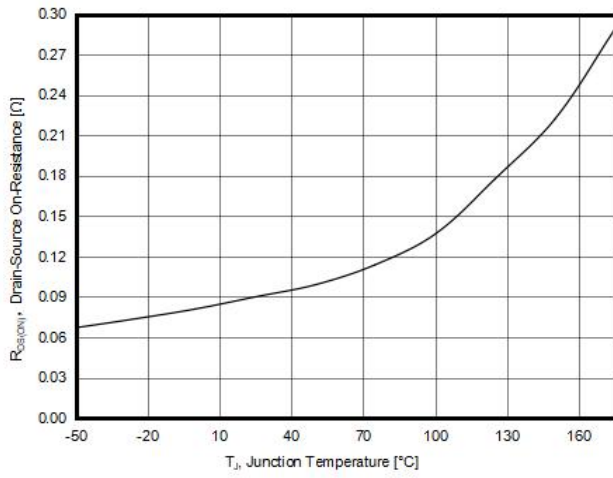


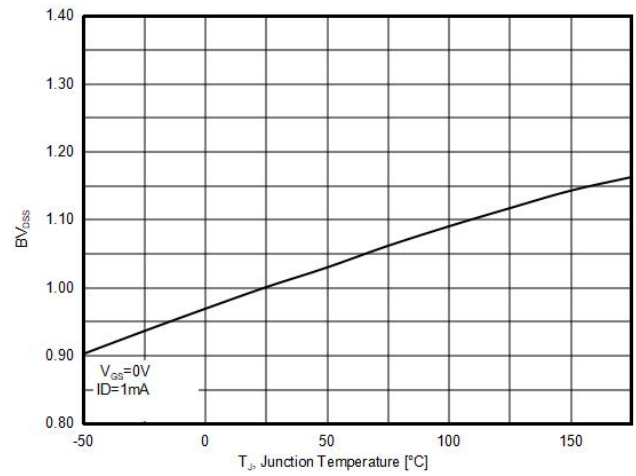
Figure6. Transfer characteristics



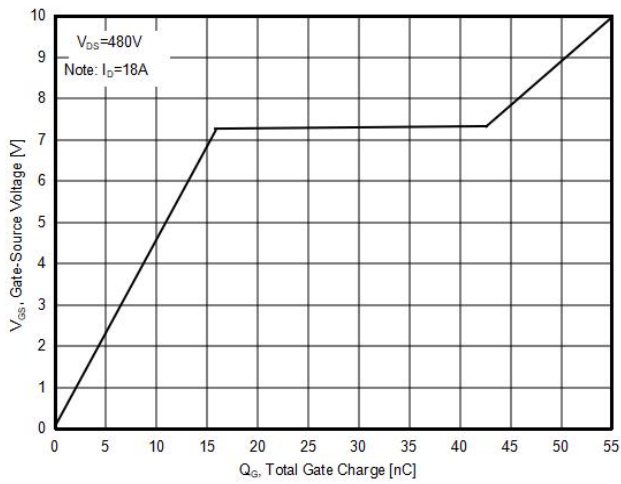
**Figure7.  $R_{DS(ON)}$  vs Junction Temperature**



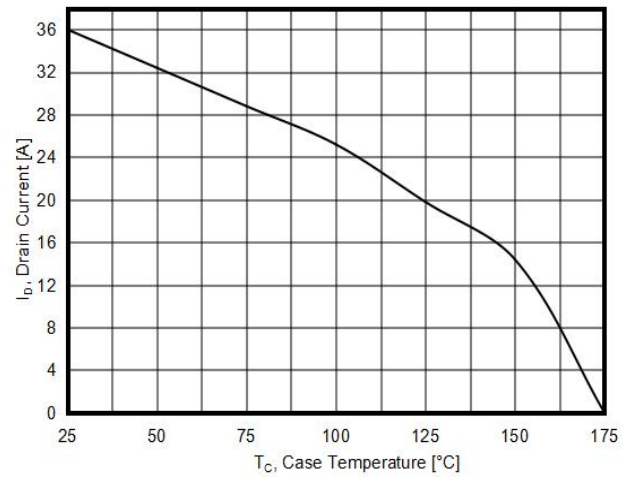
**Figure8.  $BV_{DSS}$  vs Junction Temperature**



**Figure9. Gate charge waveforms**

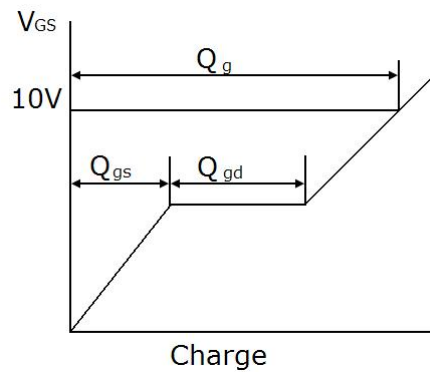
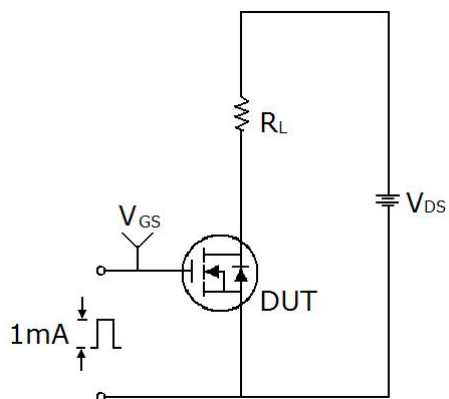


**Figure10. Maximum  $I_D$  vs Junction Temperature**

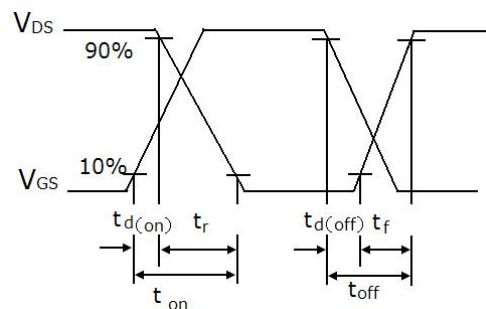
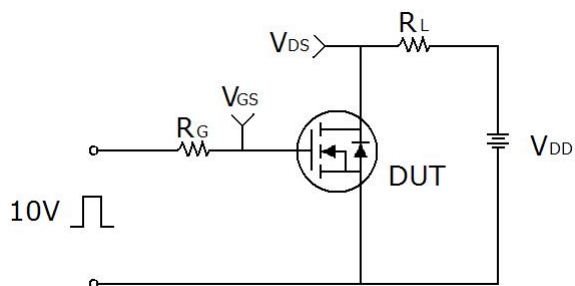


## Test circuit

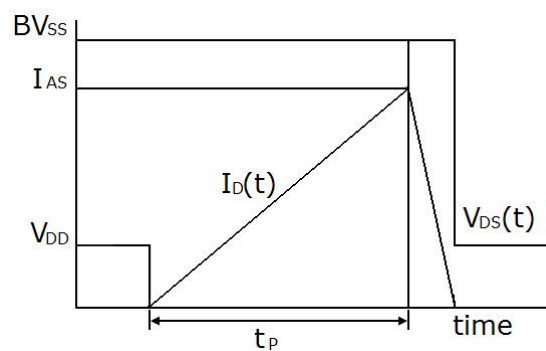
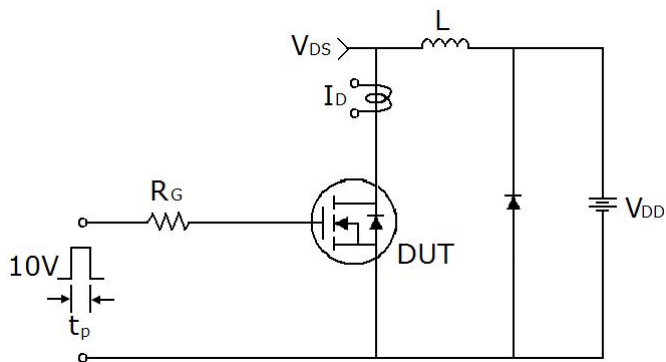
### 1) Gate charge test circuit & Waveform



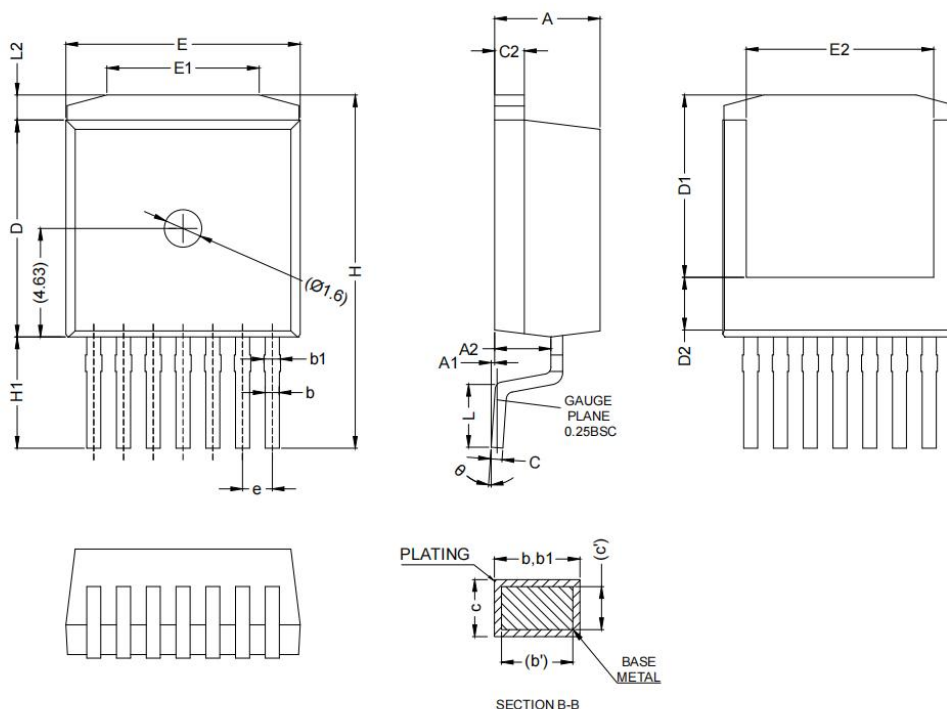
### 2) Switch Time Test Circuit:



### 3) Unclamped Inductive Switching Test Circuit & Waveforms



## TO-263-7L (B) Package Information



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min.                      | Max.  | Min.                 | Max.  |
| A      | 4.30                      | 4.70  | 0.169                | 0.185 |
| A1     | -                         | 0.25  |                      | 0.010 |
| A2     | 2.20                      | 2.60  | 0.087                | 0.102 |
| b      | 0.52                      | 0.72  | 0.020                | 0.028 |
| b'     | 0.50                      | 0.70  | 0.020                | 0.028 |
| b1     | 0.60                      | 0.80  | 0.024                | 0.031 |
| c      | 0.42                      | 0.62  | 0.017                | 0.024 |
| c'     | 0.40                      | 0.60  | 0.016                | 0.024 |
| c2     | 1.07                      | 1.47  | 0.042                | 0.058 |
| D      | 9.05                      | 9.45  | 0.356                | 0.372 |
| D1     | 7.58                      | 7.98  | 0.298                | 0.314 |
| D2     | 2.05                      | 2.45  | 0.081                | 0.096 |
| e      | 1.27BSC                   |       | 1.27BSC              |       |
| E      | 9.80                      | 10.20 | 0.386                | 0.402 |
| E1     | 6.30                      | 6.70  | 0.248                | 0.264 |
| E2     | 7.80                      | 8.20  | 0.307                | 0.323 |
| L      | 2.48                      | 2.88  | 0.098                | 0.113 |
| L2     | 0.87                      | 1.27  | 0.034                | 0.050 |
| H      | 14.87                     | 15.27 | 0.585                | 0.601 |
| H1     | 4.55                      | 4.95  | 0.179                | 0.195 |

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